ABSOLUTE MAXIMUM RATINGS

Supply Voltage (V _{CC}) to GND0.3V to +6V Control Input Voltage (RE, DE, DI, SHDN, TXP, RXP)	SO (derate 8.33mW/°C above +70°C)
to GND0.3V to (V _{CC} + 0.3V)	Operating Temperature Range
Driver Output Voltage (Y, Z) to GND8V to +13V	MAX346_C0°C to +70°C
Receiver Input Voltage (A, B) to GND8V to +13V	MAX346_E40°C to +85°C
Differential Driver Output Voltage (Y - Z)±8V	Junction Temperature+150°C
Differential Receiver Input (A - B)±8V	Storage Temperature Range65°C to +150°C
Receiver Output Voltage (RO) to GND0.3V to (V _{CC} + 0.3V)	Lead Temperature (soldering, 10s)+300°C
Output Driver Current (Y, Z)±250mA	Soldering Temperature (reflow)
Continuous Power Dissipation ($T_A = +70^{\circ}C$)	Lead(Pb)-Free+260°C
SO (derate 5.88mW/°C above +70°C)471mW	Containing Lead(Pb)+240°C
DIP (derate 9.09mW/°C above +70°C)727mW	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{CC} = +5V \pm 5\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$ Typical values are at $V_{CC} = +5V \text{ and } T_A = +25^{\circ}C.)$ (Note 1)

PARAMETER	SYMBOL	CONDIT	TONS	MIN	TYP	MAX	UNITS
Power-Supply Range	Vcc			4.75		5.25	V
DRIVER				•			
Differential Driver Output (No Load)	V _{OD}	Figure 5, R = ∞				Vcc	V
Differential Driver Output	V _{OD}	Figure 5, $R = 27\Omega$		2.1			V
Change in Magnitude of Differential Output Voltage	ΔV _{OD}	Figure 5, $R = 50\Omega$ or 2	7Ω (Note 2)			0.2	V
Driver Common-Mode Output Voltage	Voc	Figure 5, R = 50Ω or 2	7Ω			3	V
Change in Magnitude of Common-Mode Voltage	ΔV _{OC}	Figure 5, R = 50Ω or 27Ω (Note 2)			_	0.2	V
Input High Voltage	VIH	DE, DI, RE, SHDN		2.0			V
Input Low Voltage	VIL	DE, DI, RE, SHDN				0.8	V
Input Hysteresis	V _{HYS}	DE, DI, RE, SHDN			50		mV
Output Leakage (Y and Z) Full Duplex	IO	DE = GND, V _{CC} = GND or +5.25V	$V_{IN} = +12V$ $V_{IN} = -7V$	-100		+125	μΑ
Input Current	IIN	DI, RE, DE, SHDN	1114	100		±1	μΑ
Pulldown Current		RXP = TXP = V _{CC}		5	15	30	μA
Driver Short-Circuit Output		$0 \le V_{OUT} \le +12V$, outp	ut low			+250	
Current (Note 3)	IOSD	I_{OSD} $-7V \le V_{OUT} \le V_{CC}$, output high -250		-250			mA
Driver Short-Circuit Foldback	1	$(V_{CC} - 1V) \le V_{OUT} \le +$	12V, output low	+25			^
Output Current (Note 3)	IOSFD	$-7V \le V_{OUT} \le +1V$, output high		output high		-25	mA
Thermal Shutdown Threshold					140		°C
RECEIVER							
Differential Input Capacitance	C _A , B	Between A and B			8		рF
Input Current (A and B) Full Duplex	IA, B	DE = GND, V_{CC} = GND or +5.25V	$V_{IN} = +12V$ $V_{IN} = -7V$	-200		+250	μA

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = +5V \pm 5\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$ Typical values are at $V_{CC} = +5V \text{ and } T_A = +25^{\circ}C.)$ (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Receiver Differential Threshold Voltage	V _{TH}	-7V ≤ V _{CM} ≤ +12V	-200	-125	-50	mV
Receiver Input Hysteresis	ΔV_{TH}	$V_{CM} = 0$		20		mV
Receiver Output High Voltage	VoH	$I_O = -4mA$, $V_A - V_B = V_{TH}$	V _{CC} - 1.5	5		V
Receiver Output Low Voltage	V _{OL}	$I_O = 4mA$, $V_B - V_A = V_{TH}$			0.4	V
Three-State Output Current at Receiver	lozr	$0 \le V_O \le V_{CC}$			±1	μΑ
Receiver Input Resistance	RIN	-7V ≤ V _{CM} ≤ +12V	48			kΩ
Receiver Output Short-Circuit Current	IOSR	0 ≤ V _{RO} ≤ V _{CC}	±7		±95	mA
ESD Protection		A, B, Y, and Z pins (MAX3467/MAX3468/MAX3469)		±6		kV
SUPPLY CURRENT						
Normal Operation (Static Condition)	IQ	No load, DI = V _{CC} or DI = GND		2.5	4	mA
Supply Current in SHDN	ISHDN	DE = GND and \overline{RE} = V _{CC} , or SHDN = V _{CC}		1	10	μΑ
SWITCHING CHARACTERISTICS						
Driver Propagation Delay	t _{PLH}	Figures 6 and 7, R_{DIFF} = 54 Ω , C_L = 50pF			15	ns
Driver Differential Output Rise or Fall Time	t _R	Figures 6 and 7, R_{DIFF} = 54 Ω , C_L = 50pF			10	ns
Driver Output Skew ItpLH - tpHLI	tskew	Figures 6 and 7, R_{DIFF} = 54 Ω , C_L = 50pF, TXP = GND or open			2	ns
Driver Output Transition Skew		Guaranteed by design			1	ns
Maximum Data Rate			30	40		Mbps
Driver Enable to Output High	tzH	Figures 8 and 9, S2 closed, R _L = 500Ω , C _L = 50 pF			30	ns
Driver Enable to Output Low	tzL	Figures 8 and 9, S1 closed, $R_L = 500\Omega$, $C_L = 50 pF$			30	ns
Driver Disable Time from Low	tLZ	Figures 8 and 9, S1 closed, $R_L = 500\Omega$, $C_L = 50pF$			30	ns
Driver Disable to Output High	tHZ	Figures 8 and 9, S2 closed, R _L = 500Ω , C _L = 50 pF			30	ns
Driver Enable Skew Time	It _{ZL -} t _{ZH} I	$R_L = 500\Omega$, $C_L = 50$ pF, S1 closed (Figures 8 and 9), output low			5	ns
Driver Disable Skew Time	lt _{ZL -} t _{ZH} l	$R_L = 500\Omega$, $C_L = 50pF$, S2 closed (Figures 8 and 9), output high			5	ns
Receiver Propagation Delay	t _{PLH}	Figure 10, C _L = 15pF (Note 4)			20	ns

ELECTRICAL CHARACTERISTICS (continued)

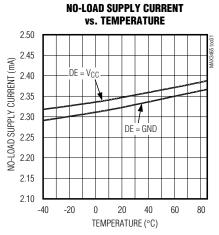
 $(V_{CC} = +5V \pm 5\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$ Typical values are at $V_{CC} = +5V \text{ and } T_A = +25^{\circ}C.)$ (Note 1)

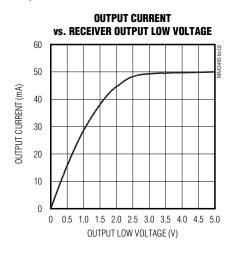
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Receiver Output Skew	It _{PLH} - t _{PHL} I	Figure 10, $C_L = 15pF$, RXP = GND or open (Note 4)			2	ns
Receiver Enable to Output Low	tzL	Figures 8 and 11, $R_L = 1k\Omega$, $C_L = 15pF$, S1 closed (Note 4)			30	ns
Receiver Enable to Output High	tzH	Figures 8 and 11, $R_L = 1k\Omega$, $C_L = 15pF$, S2 closed (Note 4)			30	ns
Receiver Disable Time from Low	t _{LZ}	Figures 8 and 11, $R_L = 1k\Omega$, $C_L = 15pF$, S1 closed (Note 4)			30	ns
Receiver Disable Time from High	tHZ	Figures 8 and 11, $R_L = 1k\Omega$, $C_L = 15pF$, S2 closed (Note 4)			30	ns
Time to Shutdown	tshdn	(Note 5)	50		800	ns
Driver Enable from Shutdown to Output High	^t ZH (SHDN)	Figures 8 and 9, R_L = 500 Ω , C_L = 50pF, S2 closed (Note 5)			4	μs
Driver Enable from Shutdown to Output Low	[†] ZL (SHDN)	Figures 8 and 9, R_L = 500 Ω , C_L = 50pF, S1 closed (Note 5)			4	μs
Receiver Enable from Shutdown to Output High	^t ZH (SHDN)	Figures 8 and 11, $R_L = 1k\Omega$, $C_L = 15pF$, S2 closed (Notes 4, 5)			4	μs
Receiver Enable from Shutdown to Output Low	[†] ZL (SHDN)	Figures 8 and 11, $R_L = 1k\Omega$, $C_L = 15pF$, S1 closed (Notes 4, 5)			4	μs

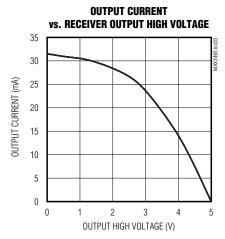
- **Note 1:** All currents into the device are positive; all currents out of the device are negative. All voltages are referenced to device ground, unless otherwise noted.
- **Note 2:** ΔV_{OD} and ΔV_{OC} are the changes in V_{OD} and V_{OC} , respectively, when the DI input changes state.
- **Note 3:** The short-circuit output current applies to peak current just prior to foldback-current limiting; the short-circuit foldback output current applies during current limiting to allow a recovery from bus contention.
- Note 4: Capacitive load includes test probe and fixture capacitance.
- Note 5: Shutdown is enabled by bringing RE high and DE low or by bringing SHDN high. If the enable inputs are in this state for less than 50ns, the device is guaranteed not to enter shutdown. If the enable inputs are in this state for at least 800ns, the device is guaranteed to have entered shutdown.

 Typical Operating Characteristics

 $(V_{CC} = +5V, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$



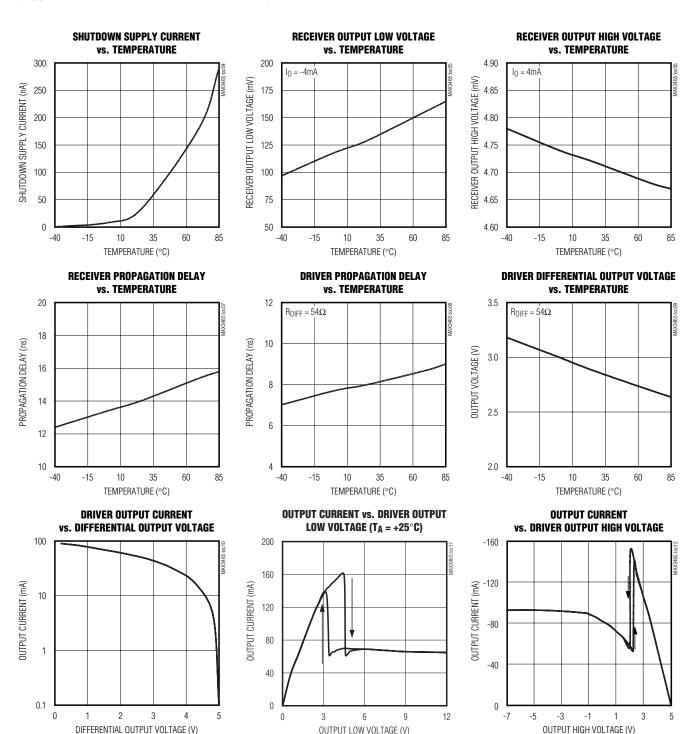




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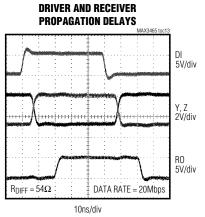
Typical Operating Characteristics (continued)

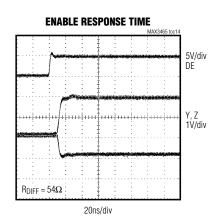
 $(V_{CC} = +5V, T_A = +25^{\circ}C, unless otherwise noted.)$

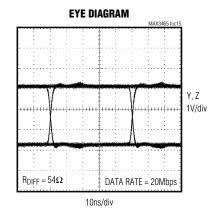


Typical Operating Characteristics (continued)

($V_{CC} = +5V$, $T_A = +25$ °C, unless otherwise noted.)







Pin Description

	PIN			
FULL D	OUPLEX	HALF DUPLEX	NAME	FUNCTION
MAX3465/ MAX3466	MAX3467	MAX3468/ MAX3469		
1	_	_	SHDN	Shutdown. Drive SHDN high to enter low-power shutdown mode.
2	2	1	RO	Receiver Output. When \overline{RE} is low and (A - B) \geq -50mV, RO is high; if (A - B) \leq -200mV, RO is low.
3	_	2	RE	Receiver Output Enable. Drive RE low to enable RO; RO is high impedance when RE is high. Drive RE high and DE low to enter low-power shutdown mode.
4	_	3	DE	Driver Output Enable. Drive DE high to enable driver output. The driver outputs are high impedance when DE is low. Drive RE high and DE low to enter low-power shutdown mode. Do not leave RE unconnected when using the MAX3466 or MAX3469.
5	3	4	DI	Driver Input. With DE high, a low on DI forces the noninverting output low and the inverting output high. Similarly, a high on DI forces the noninverting output high and the inverting output low.
6, 7	4	5	GND	Ground
8	_	_	TXP	Transmitter Phase. Connect TXP to GND, or leave unconnected for normal transmitter phase/polarity. Connect TXP to V _{CC} to invert the transmitter phase/polarity. TXP has an internal 15µA pulldown.
9	5	_	Υ	Noninverting Driver Output
10	6	_	Z	Inverting Driver Output
11	7	_	В	Inverting Receiver Input
12	8	_	Α	Noninverting Receiver Input
13	_	_	RXP	Receiver Phase. Connect RXP to GND, or leave unconnected for normal receiver phase/polarity. Connect RXP to V _{CC} to invert the receiver phase/polarity. RXP has an internal 15µA pulldown.
14	1	8	Vcc	Positive Supply: $+4.75V \le V_{CC} \le +5.25V$. Bypass V_{CC} to GND with a $0.1\mu F$ capacitor.
_		7	В	Inverting Receiver Input and Inverting Driver Output
_	_	6	А	Noninverting Receiver Input and Noninverting Driver Output

Function Tables

MAX3465/MAX3466

TRANSMITTING							
	INPUTS						PUTS
RE	DE	DI	SH	DN	7	<u>z</u>	Υ
Χ	1	1	()	()	1
Χ	1	0	()	,	1	0
0	0	Х	()	Hig	h-Z	High-Z
1	0	Х	>	(Shute	down
Χ	Х	Х	1			Shute	down
		RECI	EIVING	ì			
	I	NPUTS				0	UTPUT
RE	DE	A - E	3	SH	IDN		RO
0	Х	≥ -0.0	5V		0		1
0	Х	≤ -0.2	2V		0		0
0	Х	Open/Sh	Open/Shorted		0		1
1	1	Х	Х		0		High-Z
1	0	Х			Χ	Sh	nutdown
Х	Х	Х			1	Sł	nutdown

MAX3467

TRANSMITTING				
INPUT	OUT	PUTS		
DI	Z Y			
1	0	1		
0	1	0		
	RECEIVING			
INPUTS	OUT	PUT		
A - B	R	0		
≥ -0.05V	-	1		
≤ -0.2V	0			
Open/Shorted	-	1		

MAX3468/MAX3469

TRANSMITTING						
	INPUTS			PUTS		
RE	DE	DI	В	Α		
Χ	1	1	0	1		
Χ	1	0	1	0		
0	0	Χ	High-Z	High-Z		
1	0	Χ	Shu	tdown		
		RECE	IVING			
	II	IPUTS		OUTPUT		
RE	DE		A - B	RO		
0	Χ	≥	-0.05V	1		
0	Χ	<u> </u>	≤ -0.2V			
0	Χ	Open/Shorted		1		
1	1	Χ		High-Z		
1	0		Χ	Shutdown		

Pin Configurations and Typical Operating Circuit

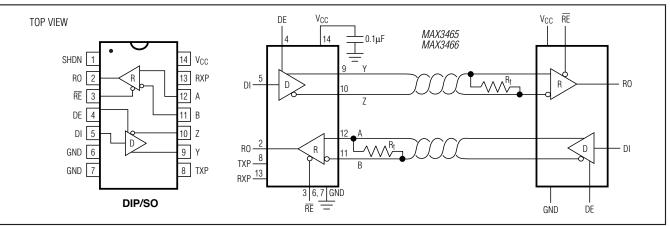


Figure 1. MAX3465/MAX3466 Pin Configuration and Typical Full-Duplex Operating Circuit

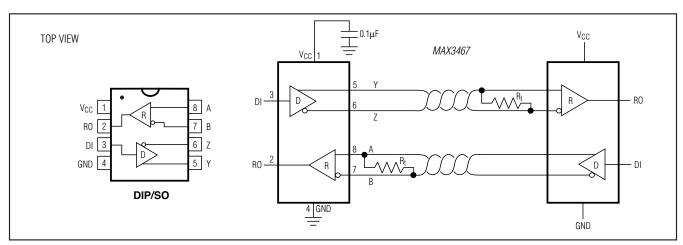


Figure 2. MAX3467 Pin Configuration and Typical Full-Duplex Operating Circuit

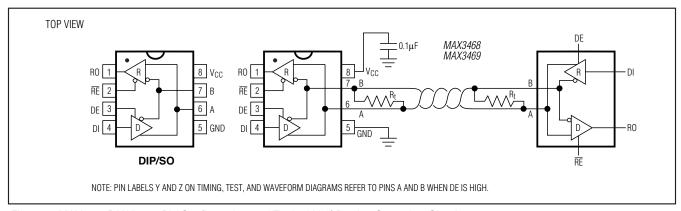


Figure 3. MAX3468/MAX3469 Pin Configuration and Typical Half-Duplex Operating Circuit

Detailed Description

The MAX3465–MAX3469 high-speed transceivers for RS-485/RS-422 communication contain one driver and one receiver. These devices feature true fail-safe circuitry, which guarantees a logic-high receiver output when the receiver inputs are open or shorted, or when they are connected to a terminated transmission line with all drivers disabled (see the *True Fail-Safe* section). The MAX3465–MAX3469's driver slew rates allow transmit speeds up to 40Mbps.

The MAX3468 and MAX3469 are half-duplex transceivers, while the MAX3465, MAX3466, and MAX3467 are full-duplex transceivers. All of these parts operate from a single +5V supply. Drivers are output short-circuit current limited. Thermal-shutdown circuitry protects drivers against excessive power dissipation. When activated, the thermal-shutdown circuitry places the driver outputs into a high-impedance state. The MAX3465 and MAX3468 devices have a hot-swap input structure that prevents disturbances on the differential signal lines when a circuit board is plugged into a hot backplane (see the *Hot-Swap Capability* section). All devices have output levels that are compatible with Profibus standards.

True Fail-Safe

The MAX3465–MAX3469 guarantee a logic-high receiver output when the receiver inputs are shorted or open, or when they are connected to a terminated transmission line with all drivers disabled. This is done by setting the receiver threshold between -50mV and -200mV. If the differential receiver input voltage (A - B) is greater than or equal to -50mV, RO is logic high. If A - B is less than or equal to -200mV, RO is logic low. In the case of a terminated bus with all transmitters disabled, the receiver's differential input voltage is pulled to 0V by the termination. With the receiver thresholds of the MAX3465–MAX3469, this results in a logic high with a 50mV minimum noise margin. Unlike previous true fail-safe devices, the -50mV to -200mV threshold complies with the ±200mV EIA/TIA-485 standard.

Hot-Swap Capability

Hot-Swap Inputs

When circuit boards are inserted into a "hot" or powered backplane, disturbances to the enable and differential receiver inputs can lead to data errors. Upon initial circuit board insertion, the processor undergoes its power-up sequence. During this period, the processor output drivers are high impedance and are unable to drive the DE input of the MAX3465/MAX3468 to a

defined logic level. Leakage currents up to $10\mu A$ from the high-impedance output could cause DE to drift to an incorrect logic state. Additionally, parasitic circuit board capacitance could cause coupling of VCC or GND to DE. These factors could improperly enable the driver.

When V_{CC} rises, an internal pulldown circuit holds DE low for around 15µs. After the initial power-up sequence, the pulldown circuit becomes transparent, resetting the hot-swap-tolerable input.

Hot-Swap Input Circuitry

The MAX3465/MAX3468 enable inputs feature hot-swap capability. At the input there are two NMOS devices, M1 and M2 (Figure 4). When VCC ramps from 0, an internal 15µs timer turns on M2 and sets the SR latch, which also turns on M1. Transistors M2, a 2mA current sink, and M1, a 100µA current sink, pull DE to GND through a $5.6k\Omega$ resistor. M2 is designed to pull DE to the disabled state against an external parasitic capacitance up to 100pF that can drive DE high. After 15µs, the timer deactivates M2 while M1 remains on, holding DE low against three-state leakages that can drive DE high. M1 remains on until an external source overcomes the required input current. At this time, the SR latch resets and M1 turns off. When M1 turns off, DE reverts to a standard, high-impedance CMOS input. Whenever VCC drops below 1V, the hot-swap input is reset.

For $\overline{\text{RE}}$ there is a complementary circuit employing two PMOS devices pulling to V_{CC}.

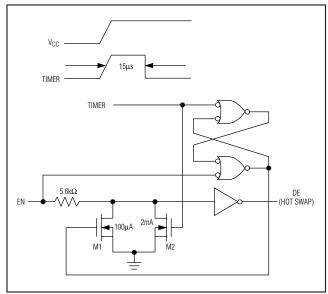


Figure 4. Simplified Structure of the Driver Enable Pin (DE)

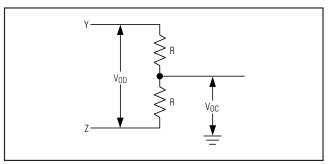


Figure 5. Driver DC Test Load

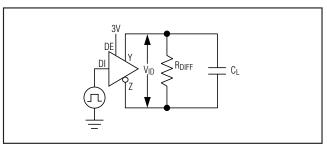


Figure 6. Driver Timing Test Circuit

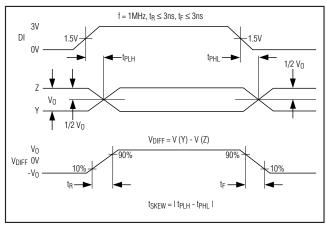


Figure 7. Driver Propagation Delays

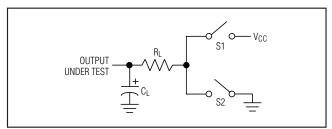


Figure 8. Enable/Disable Timing Test Load

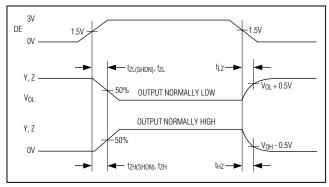


Figure 9. Driver Enable and Disable Times

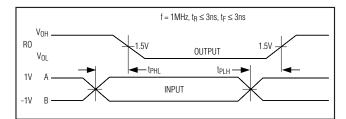


Figure 10. Receiver Propagation Delays

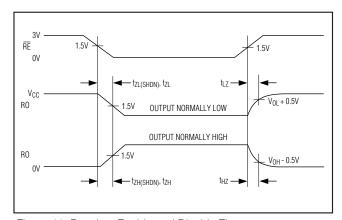


Figure 11. Receiver Enable and Disable Times

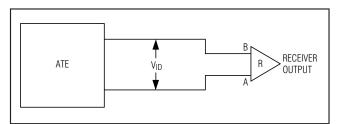


Figure 12. Receiver Propagation Delay Test Circuit

Applications Information

128 Transceivers on the Bus

The standard RS-485 receiver input impedance is $12k\Omega$ (one unit load), and the standard driver can drive up to 32 unit loads. The MAX3465–MAX3469 family of transceivers has a 1/4-unit-load receiver input impedance (48k Ω), allowing up to 128 transceivers to be connected in parallel on one communication line. Any combination of these devices and/or other RS-485 transceivers with a total of 32 unit loads or less can be connected to the line.

Low-Power Shutdown Mode (Except MAX3467)

Low-power shutdown mode is initiated by bringing SHDN high (MAX3465/MAX3466), or both \overline{RE} high and DE low. In shutdown, the devices typically draw only 1µA of supply current. \overline{RE} and DE can be driven simultaneously; the devices are guaranteed not to enter shutdown if \overline{RE} is high and DE is low for less than 50ns. If the inputs are in this state for at least 800ns, the devices are guaranteed to enter shutdown.

Driver Output Protection

Two mechanisms prevent excessive output current and power dissipation caused by faults or by bus contention. The first, a foldback current limit on the output stage, provides immediate protection against short circuits over the whole common-mode voltage range (see the *Typical Operating Characteristics*). The second, a thermal-shutdown circuit, forces the driver outputs into a high-impedance state if the die temperature exceeds +140°C.

Propagation Delay

Many digital encoding schemes depend on the difference between the driver and receiver propagation delay times. Typical propagation delays are shown in the *Typical Operating Characteristics*. The difference in receiver delay times, Itplh - tphl I is a maximum of 2ns. The driver skew time Itpl H - tphl I is also a maximum of 2ns.

Typical Applications

The MAX3465–MAX3469 transceivers are designed for bidirectional data communications on multipoint bus transmission lines. Figures 13 and 14 show typical network applications circuits. To minimize reflections, the line should be terminated at both ends in its characteristic impedance, and stub lengths off the main line should be kept as short as possible.

Profibus Termination

The MAX3465–MAX3469 are designed for driving Profibus termination networks. With a worst-case loading of two termination networks with 220 Ω termination impedance and 390 Ω pullups and pulldowns, the drivers can drive V_{A-B} > 2.1V output.

Chip Information

PROCESS: BICMOS

_Ordering Information (continued)

PART	TEMP RANGE	PIN-PACKAGE
MAX3466CSD	0°C to +70°C	14 SO
MAX3466CPD	0°C to +70°C	14 Plastic DIP
MAX3466ESD	-40°C to +85°C	14 SO
MAX3466EPD	-40°C to +85°C	14 Plastic DIP
MAX3467CSA	0°C to +70°C	8 SO
MAX3467CPA	0°C to +70°C	8 Plastic DIP
MAX3467ESA	-40°C to +85°C	8 SO
MAX3467EPA	-40°C to +85°C	8 Plastic DIP
MAX3468CSA	0°C to +70°C	8 SO
MAX3468CPA	0°C to +70°C	8 Plastic DIP
MAX3468ESA	-40°C to +85°C	8 SO
MAX3468EPA	-40°C to +85°C	8 Plastic DIP
MAX3469CSA	0°C to +70°C	8 SO
MAX3469CPA	0°C to +70°C	8 Plastic DIP
MAX3469ESA	-40°C to +85°C	8 SO
MAX3469EPA	-40°C to +85°C	8 Plastic DIP

Devices are also available in a lead(Pb)-free/RoHS-compliant package. Specify lead-free by adding "+" to the part number when ordering.

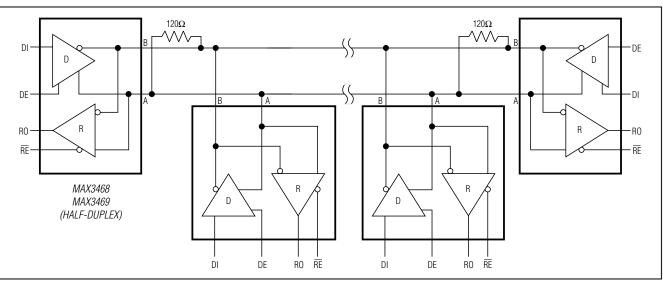


Figure 13. Typical Half-Duplex RS-485 Network

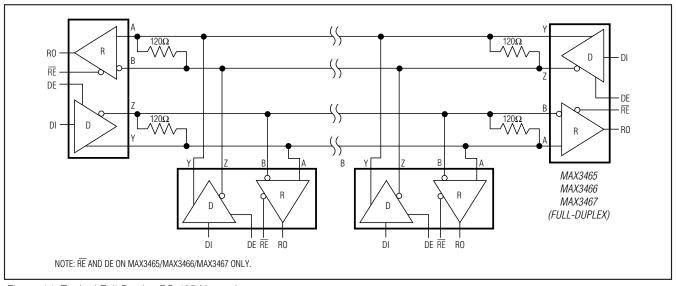


Figure 14. Typical Full-Duplex RS-485 Network

Package Information

For the latest package outline information and land patterns (footprints), go to www.maxim-ic.com/package. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
14 SO	S14-1	<u>21-0041</u>	<u>90-0112</u>
14 PDIP	P14-3	<u>21-0043</u>	_
8 SO	S8-2	<u>21-0041</u>	90-0096
8 PDIP	P8-1	21-0043	_

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	10/09	Initial release.	_
1	1/04	Updated the description for the DE pin in the Pin Description table.	6
2	8/09	Replaced TOC 11.	5
3	5/12	Added lead-free compliant packaging information, updated Figure 3 caption, updated package table	1, 8, 11, 12

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